## DECLARATION FOR PATENT APPLICATION AND POWER OF ATTORNEY

(Under 37 CFR § 1.63; includes reference to PCT International Applications)

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention ENTITLED:

METHOD OF PREPARING CARBON NANOTUBE FROM LIQUID PHASED-CARBON SOURCE

the specification	n of which:			
	PCT Application No. PC	ontinuation or Co T/KR2004/00074 and published as	ontinuation-in-Part or Division 45, filed March 31, 2004 S WO 2004/087565 A on Oc	
I hereb	y state that I have reviewe laims, as amended by any	d and understand amendment refer	the contents of the above-ic red to above.	dentified specification,
I acknown to me to	owledge the duty to discloso be material to patentabili	se to the United S ty as defined in T	States Patent and Trademark Title 37, Code of Federal Reg	Office all information gulations, § 1.56.
application(s) f one country oth application for country other th	or patent or inventor's cert ner than the United State of patent or inventor's certific	ificate or of any if America listed locate or any PCT if merica filed by n	e 35, United States Code § 1 PCT International application below and have also identifications de international applications de the on the same subject matter ed:	on(s) designating at least ed below any foreign signating at least one
Prior Foreign/P	PCT Application(s) [list ad	ditional applicati	ons on separate page]:	Priority Claimed:
Country (or South Korea			Filed (Day/Month/Year) 02/04/2003	Yes No
I hereby claim the benefit under 35 U.S.C. §119(e) of any United States application listed below:				
(Applie	cation Number)	(Filing Date)		
or PCT internation	tional application(s) design	nating the United	States Code § 120 of any Un States of America that is/ar on is not disclosed in that/th	e listed below and, insofar

the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the

filing date of the prior application and the national or PCT international filing date of this application:

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Prior U.S. (or U.S.-designating PCT) Application(s) [list additional applications on separate page]:

U.S. Serial No.: Filed (Day/Month/Year) PCT Application No. Status (patented, pending, abandoned)

I hereby appoint Ronald R. Santucci, Registration No. 28,988, and Frommer Lawrence & Haug LLP, or their duly appointed associate, my attorneys, with full power of substitution and revocation, to prosecute this application, to make alterations and amendments therein, to file continuation and divisional applications thereof, to receive the Patent, and to transact all business in the Patent and Trademark Office and in the Courts in connection therewith, and to insert the Serial Number of the application in the space provided above, and specify that all communications about the application are to be directed to the following correspondence address:

Ronald R. Santucci, Esq. c/o FROMMER LAWRENCE & HAUG LLP 745 Fifth Avenue New York, NY 10151

Direct all telephone calls to: (212) 588-0800 to the attention of: Ronald R. Santucci

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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